

Dual 2:1 USB2.0 Mux/De-Mux with DC 30V Over-Voltage Protection

Descriptions

The RLCS6743 is a bidirectional low-power dual port, high-speed, USB 2.0 analog switch with integrated protection for USB Type-C™ systems. The device is configured as a dual 2:1 or 1:2 switch. It is optimized for use with the USB 2.0 DP/DM lines in a USB Type-C™ system.

The RLCS6743 integrated over-voltage protection on the D+/- pins can withstand up to DC 30V with automatic shutoff circuitry in order to protect system components behind the switch. GPIO controls of S1, S2 and OE are 1.8V logic compatible. The RLCS6743 is available in 12 Ball Wafer Level Chip Scale Package (WLCSP) with and spa 1.2x1.6x0.6mm with Pb-free and Halogen-free making it a perfect candidate for mobile and space constrained applications.

Features

- 12-Ball WLCSP 1.2mm x 1.6mm
- Supply Range 2.5 V to 5.5 V
- Differential 2:1 or 1:2 Switch/Multiplexer
- Up to DC 30V Overvoltage Protection (OVP) on D+/- Ports
- IEC 64000-4-5 Surge Protection w/o External TVS onto D+/- Ports: ±30V
- System Side Clamp Voltage Pulse Less than 9V, Duration Less than 200nS
- Powered Off Protection When VCC = 0 V
- Low RON of 10 Ω Typical
- Insertion loss: -1dB@200MHz, -2dB@650MHz, -3dB@1GHz \triangleright
- CON of 4.8 pF
- 1.8-V Compatible Logic Inputs
- Standard Temperature Range of 0°C to 85°C

Applications

- Anywhere a USB Type-C™ or Micro-B Connector is Used
- **Mobile Phones**
- **Tablets and Notebooks**



Functions and Pin Configuration

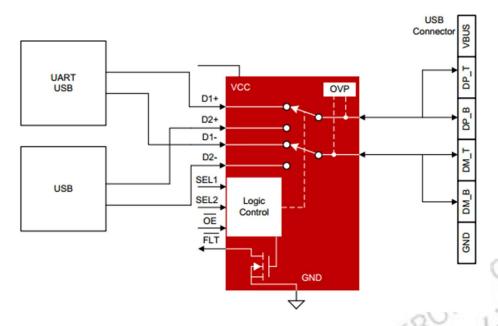


Fig.1 Functional Diagram

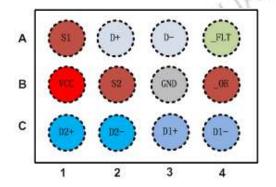


Fig.2 Top-Through View

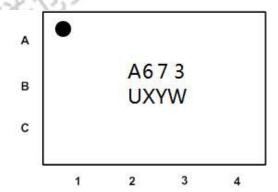


Fig.3 Top Side Marking View



Pin Descriptions

Pin	Name	Туре	Description	on	
A1	S1	I	Switch Select 1 (Active High)		
A2	D+	I/O	Data switch input (Differential	+)	
A3	D-	I/O	Data switch input (Differential	-)	
A4	_FLT	0	Fault indicator output (Active L	Low) open drain	
B1	VCC	PWR	Power Supply		
B2	S2	I	Switch Select 2 (Active High)		
В3	GND	GND	Ground		
B4	_OE	I	Output Enable (Active Low)	-0	
C1	D2+	I/O	Data switch output 2 (Different	tial +)	
C2	D2-	I/O	Data switch output 2 (Different	tial -)	
C3	D1+	I/O	Data switch output 1 (Differential +)		
C4	D1-	I/O	Data switch output 1 (Differential -)		
	der Information	ble-1 Pin Desc	CHUANGEL	3 TABRELL	
Ord					
Ord	Packaç	e)	Part Number	Quantity Per Reel	

Table-1 Pin Descriptions

Order Information

Packa	Package		Quantity Per Reel		
WLCSP1.2x1.6-12Ball	Tape and Reel	RLCS6743WL12/R6	3,000PCS		

Electrical Characteristics (Ta=25°C, VCC=3.3V, unless otherwise specified)

Parameter Symbol	Conditions	Min.	Тур.	Max.	Unit
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POWER SUPPLY						
Supply Voltage Range	V _{CC}		2.5	3.3	5.5	V
		_OE =1 disconnection		0.6	2	uA
Supply Current	Icc	_OE =0 connection		33		uA
S1/S2/_OE DIGITAL INPUT CO	NTOL					
control input logic high	V _{IH}		1.6		5.5	V
control input logic low	V _{IL}		-0.1		0.5	V
Internal pull-down resistor	R _{PD}			2		ΜΩ
SWITCH ON RESISTANCE AND O	FF LEAKAGE					
On-Resistance	Ron	V _{IS} = 0V~0.4V I _{OUT} =8mA		10	11	Ω
Ron Flatness ⁽¹⁾	R _{FLAT}	V _{IS} = 0V~0.4V I _{OUT} =8mA		0.3	0.5	Ω
R _{ON} Matching Between Channels ⁽²⁾	ΔR _{ON}	V _{IS} = 0V~0.4V I _{OUT} =8mA		0.1	0.2	Ω
OFF Leakage Current	I _{LEAK}	V _{D+/-} = 10V V _{D1+/-} = V _{D2+/-} =0V		31	50	uA
SWITCH DYNAMICS				- 0		
On Capacitance	Con	V _{D+/-} = 0.2V, f = 1MHz	2	4		pF
Off Capacitance	C _{OFF}	V _{D+/-} = 0.2V, f = 1MHz	20/	3	(2)	pF
Off Isolation	Off	$f = 250MHz$, $R_T = 50Ω$, $C_L = 0pF$	5	-38		dB
Crosstalk ⁽³⁾	· ·	f - 250MH= D - 500 C - 0×5	-13	41		dB
(Channel-to-Channel)	X _{TALK}	$f = 250MHz$, $R_T = 50Ω$, $C_L = 0pF$	SI	-41		иь
-3dB Bandwidth	BW	R _T =50Ω, C _L =0pF Signal Power 0dBm	0.9	1		GHz
Break-Before-Make	BBM	$V_{D1+/-} = V_{D2+/-} = 0.4V$, $R_L = 50\Omega$		1.5		uS
Turn-on Time	t _{OFF}	$V_{D+/-} = 0.4V$, $R_L = 50\Omega$ _OE switches from High to Low		20		uS
Turn-off Time	t _{OFF}	$V_{D+/-} = 0.4V$, $R_L=50\Omega$ _OE switches from Low to High		1.2		uS
Propagation Delay	t _{PD}	$V_{D+/-} = 0.4V$, $R_L = 50\Omega$		200		pS
OVER VOLTAGE PROTECTION	(30)		•	-	•	
OVP Lockout Threshold	V _{OVP}	V _{D+/-} Rising Edge	4.6	4.9	5.2	V
OVP Hysteresis	V _{HYS}	V _{D+/-} Falling Edge		200		mV
Clamp Voltage on D _{1+/-} and D _{2+/-}	V _{CLAMP}	10V shorts to $D_{+/-}$ with R_L =1K Ω @ $D_{1+/-}$ and $D_{2+/-}$		6.5	8	V
OVP Response Time	t _{FP}	10V shorts to $D_{+/-}$ with R_L =1K Ω @ $D_{1+/-}$ and $D_{2+/-}$		200	300	nS
OVP Recovery Time	t _{FPR}	V _{D+/-} jumps from 6V to 1V step	30	45	60	uS
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Table-2 Electrical Characteristics

Note:

- (1) Flatness is defined as the difference between maximum and minimum value of ON-resistance at the specified analog signal voltage points.
- (2) R_{ON} matching between channels is calculated by subtracting the channel with the lowest max Ron value from the channel with the highest max Ron value.
- (3) Crosstalk is inversely proportional to source impedance

Typical Performance Curves (Ta=25°C, VCC=3.0V, CAP=0.1uF, unless otherwise noted)



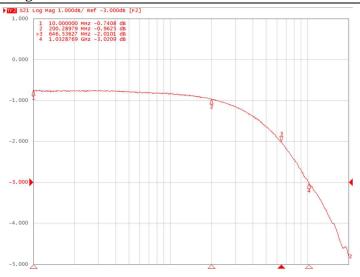


Fig.4 Switch Bandwidth or Insertion Loss

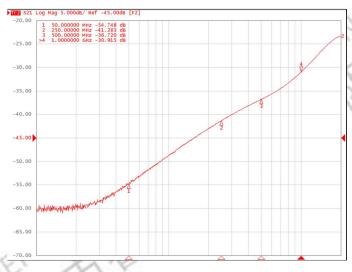


Fig.5 Switch Channel to Channel Cross-Talk

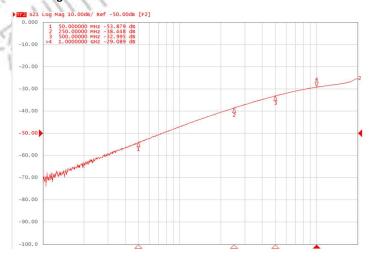


Fig.6 Switch Off Isolation

Package Outline Dimensions



WLCSP-12B

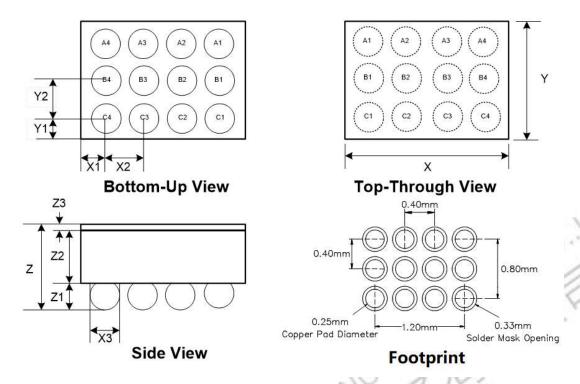


Fig-7 Package Outline Dimensions

	RUILIANCE	K BIJIE		
Symbol	Dimensions In Millimeter			
Symbol	Min.	Тур.	Max.	
X	1.58	1.6	1.62	
CKX -3	1.18	1.2	1.22	
X1	1	0.20		
X2		0.40		
Х3	0.21	0.23	0.25	
Y1		0.20		
Y2		0.40		
Z	0.525	0.575	0.625	
Z1	0.165	0.185	0.205	
Z2	0.340	0.365	0.390	
Z3	0.020	0.025	0.030	

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